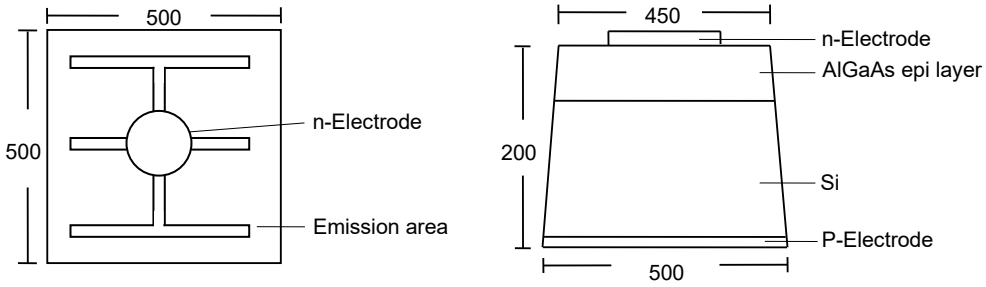
Features :

- Suitable for New Creative Products
- High Power
- High Performance
- Superior Thermal Stability

Typical Applications :

- Night Vision
- Camera
- Outdoor/Indoor applications

Outline Dimensions : (Unit: um)



Physical Structure :

LED Chip dimension	Chip size	500 um x 500 um
	Thickness	200 ± 25 um
	Emission area	450 um
	Bonding pad	125 um
Electrode	Top: N (cathode)	Gold
	Backside: P (anode)	Gold

*C

Electro-Optical Characteristics : (Ta = 25℃)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward voltage	V_{FH}	I_F = 150 mA	2.60	-	3.0	V
Reverse current	I_R	V_R = 10V	-	-	1	μA
Radiant Power	P_o	I_F = 150 mA	60	-	90	mW
Wavelength	λ_P	I_F = 150 mA	940	-	950	nm
Spectral width at half height	△λ	I_F = 150 mA	-	35	-	nm

Typical Electro-Optical Characteristics Curve:

Fig 1. Forward Current vs. Forward Voltage

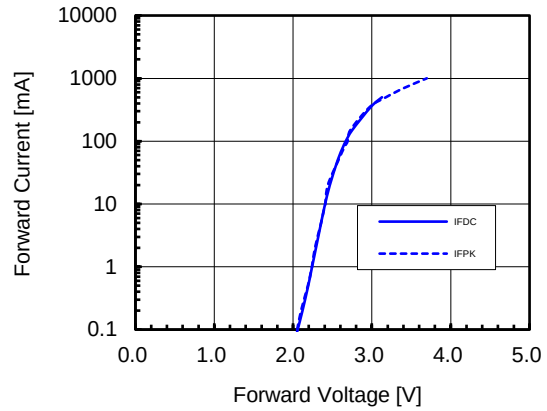


Fig 2. Relative Radiant Power vs. Wavelength

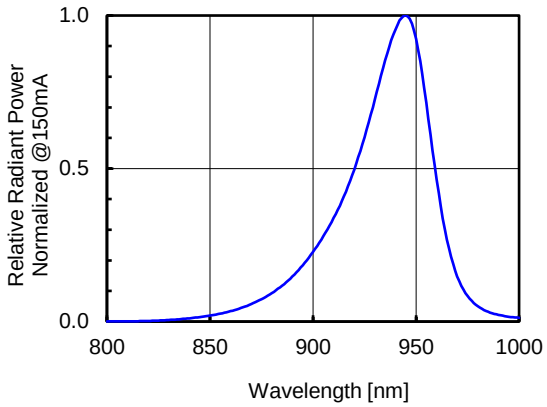


Fig 3. Relative Radiant Power vs. Forward DC Current

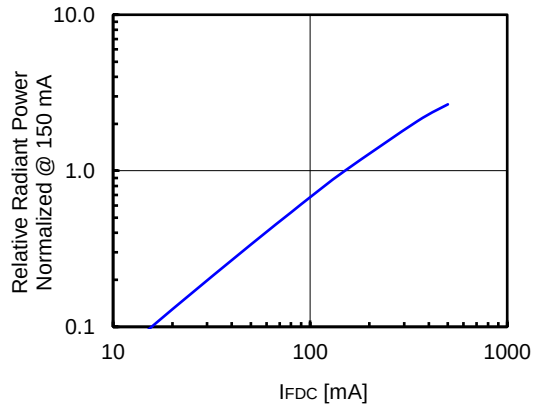


Fig 4. Relative Radiant Power vs. Forward Peak Current

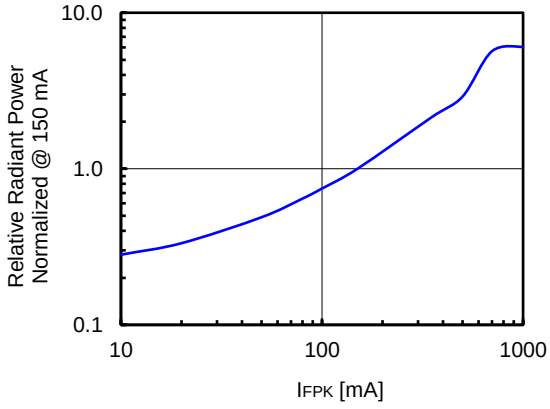


Fig 5. Forward DC Voltage vs. Temperature

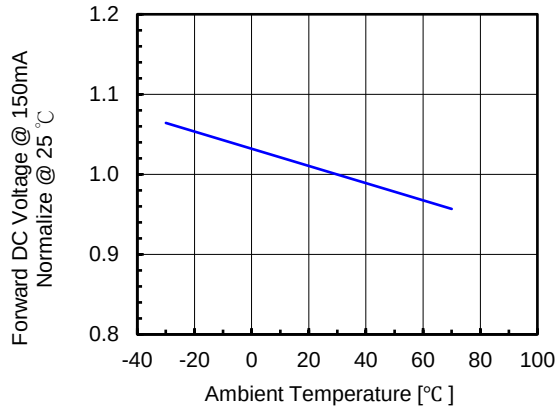


Fig 6. Relative Radiant Power vs. Temperature